INTEGRATED CIRCUIT PACKAGE EMPLOYING FLIP-CHIP TECHNOLOGY AND METHOD OF ASSEMBLY

ABSTRACT OF THE DISCLOSURE

An integrated circuit package includes a package substrate having a first surface including a first array of interconnection sites and a second array of interconnection sites. A first integrated circuit die has a first surface including an array of interconnection sites. A second integrated circuit die has a first surface including an array of interconnection sites. The first array of interconnection sites is electrically connected to the array of interconnection sites of the second integrated circuit die. The second array of interconnection sites is electrically connected to the array of interconnection sites of the first integrated circuit die. The first integrated circuit die is positioned amid the package substrate and the second integrated circuit die.